



Flight hardware optimisation through modularity and building blocks

ESA EDHPC
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DEFENCE AND SPACE

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AIRBUS

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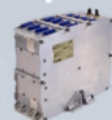
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This document has been assessed by the following Technical Rater :

Assessed and classified by: Jean-Luc Poupat

Date classification completed: 01/09/2023

Space Electronics key figures & facts



450
France workforce

> 1200 boards /y
> 150 unit /y

150 M€
Revenues
40% export



Space Agencies



Start-up,
medium & big
size companies



Institutions
and Defence
Agencies



Satellite
Operators

Governments, institutional and enterprises from
multiple areas/ fields



1st



Worldwide Leader

> 60 M€ Export
Order Intake in 2022

Spacecraft Electronic Unit Supplier



Elancourt

Toulouse

Our Ambition



Be worldwide Electronics and Sensors / Actuators
reference for Space



Master New Space & Conventional Space solutions
from design and technologies, up to manufacturing
& test processes

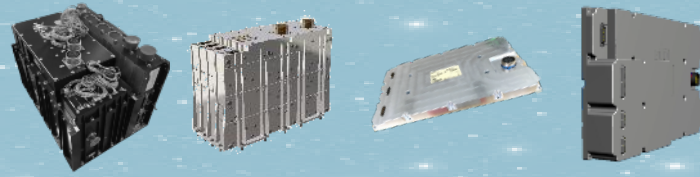


Pioneer and qualify space technologies for future
spacecrafts, launchers & space systems

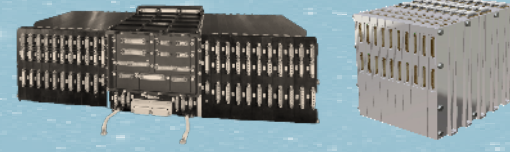


Be attractive for talents by offering key
competences acquisition and efficient collective
knowledge management

Space Electronics reliable & large unit portfolio

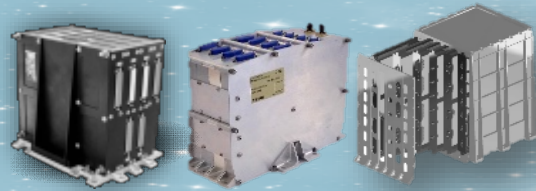


Electric Propulsion

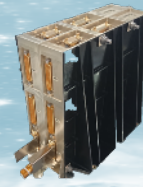


Power Distribution & Regulation

**Power &
Propulsion Units**



On-board Computers

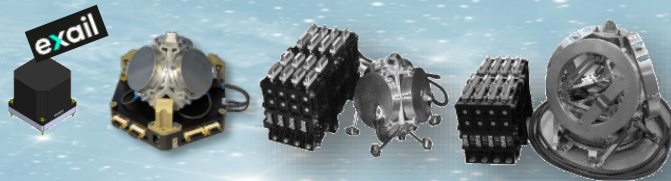


Security

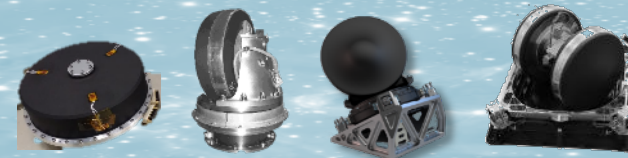


Payload Data Handling

**Platform & Payload
Processing Units**



Fiber Optic Gyroscopes



Control Moment Gyroscope

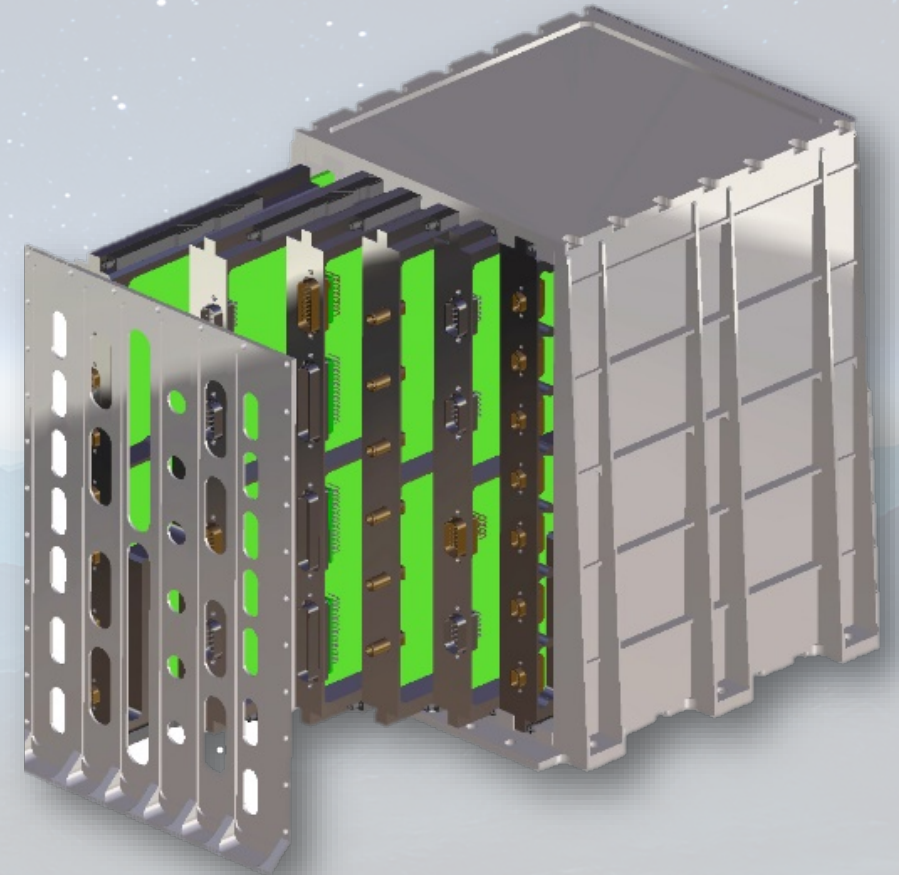
**Sensors &
Actuators**

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Advantages of Modularity

Main advantages to standardize modular architecture

- Shorter development time
- Merge of Modules from different providers
- SW development improvement thanks to the use of standardized interfaces



Example of Modular OBC

Baseline Version

**Power
Module**



**Processor
Module**



**Companion
Module**



Extended Version

**GNSS
Module**



**Telecom
Module**



All modularity **features not used** in orbit life

Increase of the electronic functions size

- Local power distribution
 - All local power shall be generated and not shared on the backplane
- Backplane Interface electrical drivers

Increase of volume and weight

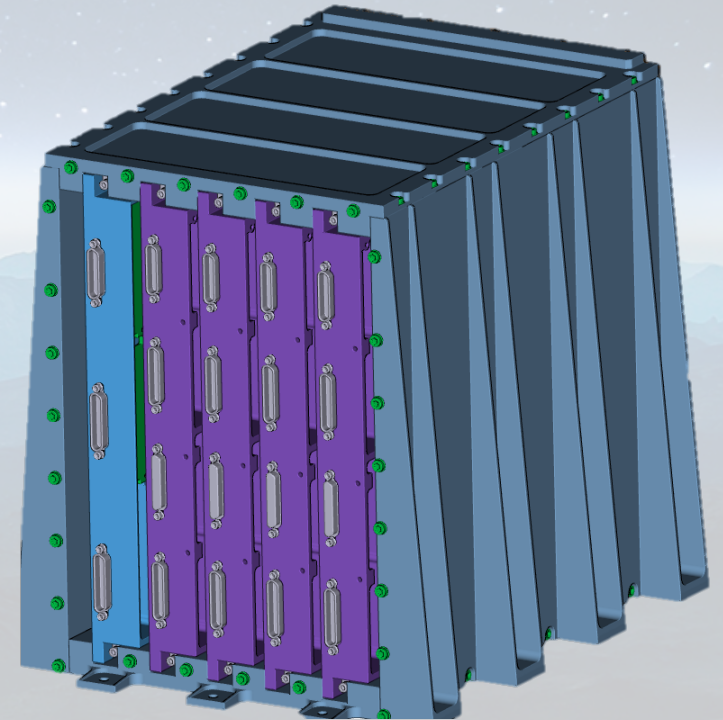
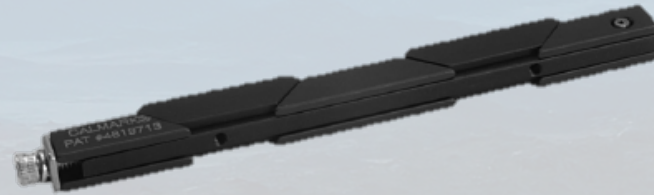
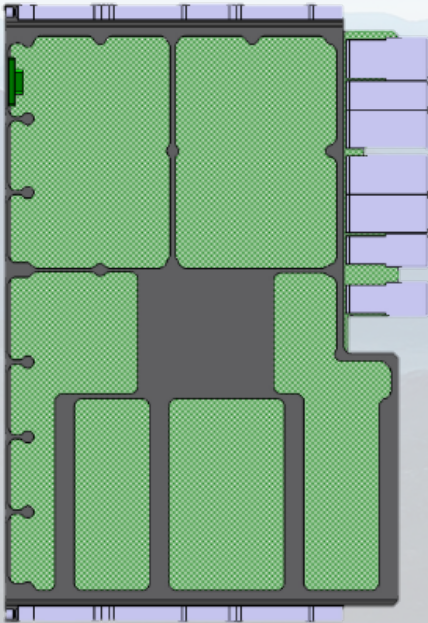
- Mechanical features for rack

Generally **only one face of the unit reserved for connectors**

Standardization - Physical Impacts

Standardization leads to **increase the mass and the size** (for a 6U extended cPCI):

- Weight more than 2 kg per module
- Frame alignment needs specific hardware (wedge-lock)



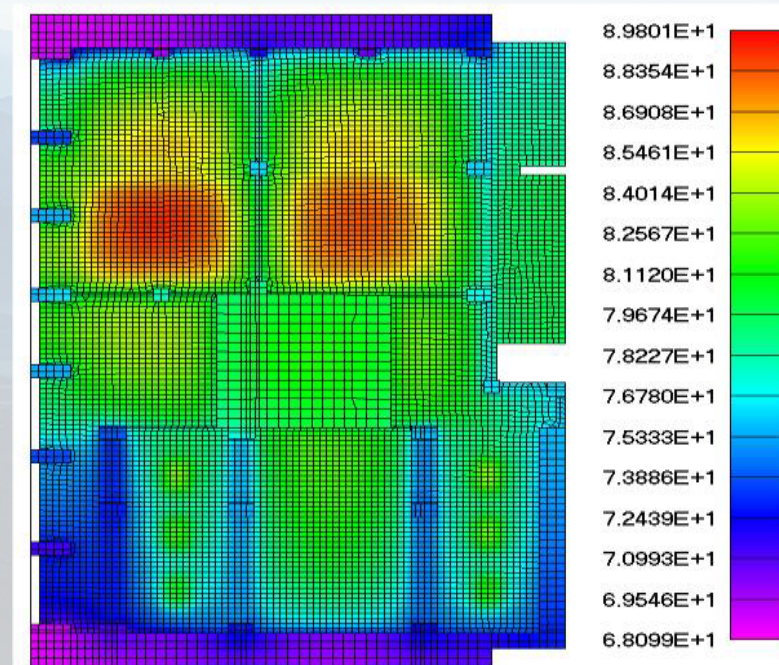
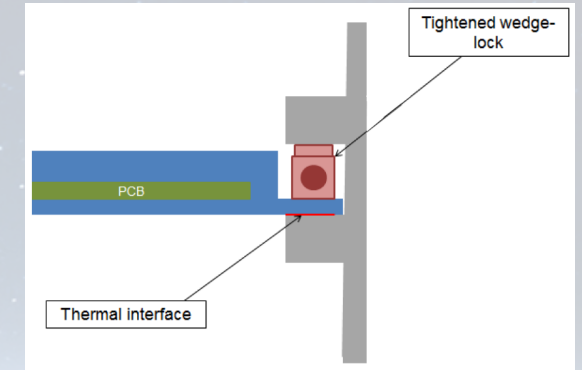
Standardization leads to **decrease electrical interfaces** (on back-plane):

- Use of limited interfaces and buses : i.e. CAN, SpW, SpF
- Preference for serial communications
- Increase of data rate using on serial
- Power distribution on a single shared intermediate voltage.

Standardization - Thermal Impacts

The use of standardized modules may limit the power dissipation

- The locking and alignment hardware is generally the only thermal interface to the frame
- Limit of power dissipation around 30W per module



The **use of new SoC technologies** gives benefits to modularity

- Very high integration of the of the SoC (System on Chip)
- Reconfigurability even in space (FPGA)
- High processor performances

BUT:

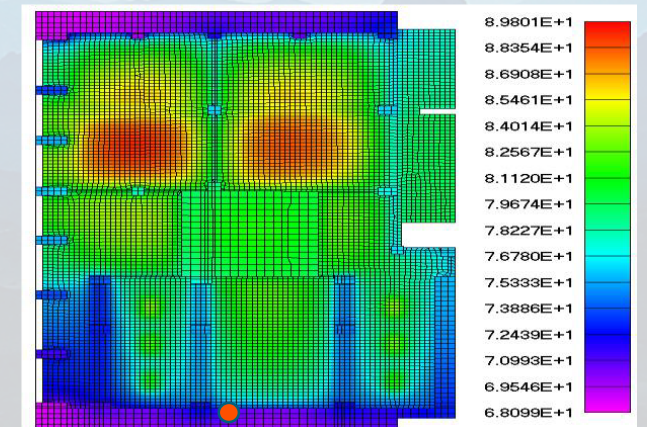
- The modularity can limits the use of some interfaces of the SoC
=> use of HSSL and serial protocol to transmit data
- The local power distribution is complex and taking into account FDIR can be expensive in PCB surface
=> Use of integrated POL



Qualification of modules

How to consider a module as **qualified at module level** (regarding the integration in a unit)

- **Test communication interfaces with margins on the back-plane interfaces**
 - Use standard worst case backplane to test interfaces between modules
 - Measure of signal at module to back-plane interface
- **It shall dissipate heat by the mechanical interfaces**
 - Proposal of a standardized module TRP with a position at the mechanical interface for thermal analysis
- **It shall be compliant with a standard vibration and shocks**
 - Use of a standard frame giving the mechanical constraints at module level



Standard Module TRP

Taking into account that a **qualified module can be relaxed to:**

- Hardware software integration
- Electrical test on serial interface by test at maximum speed
- During thermal test verify the local TRP at each module
- Mechanical tests

Development

- The modularity shall be at functional level i.e avoid merging different functions on one module
- Use preferably serial interface and only standardize interfaces on backplane
- Limit the power dissipation

Qualification

- Standardize the tests done at module level
- Margins shall be integrated on test results
- Use of a standard worst case frame for test

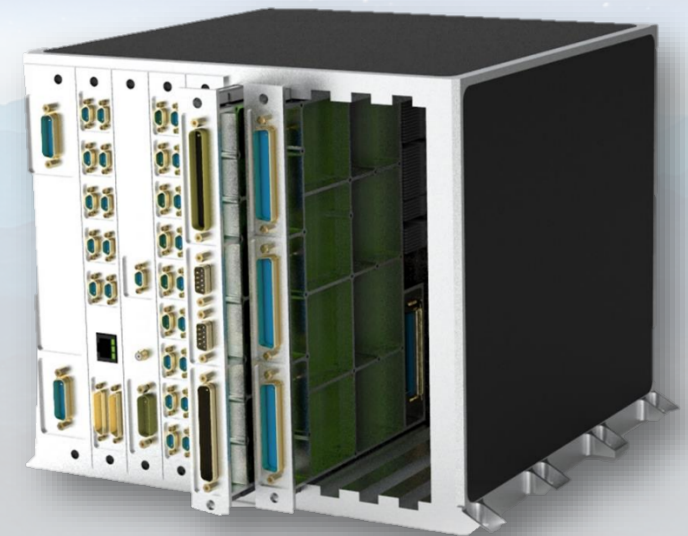


Illustration picture from ADHA working group

Thank you

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